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| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. | |
|------------------------|----------------------|----------------------|---------------------|------------------|--|
| 10/644,555 | 08/20/2003 | Atsushi Shozude | 19036/39398 | 6655 | |
| 4743 | 4743 7590 11/26/2004 | | | EXAMINER | |
| MARSHALI 6300 SEARS | L, GERSTEIN & BOR | CHANG, A | CHANG, AUDREY Y | | |
| 233 S. WACKER DRIVE | | | ART UNIT | PAPER NUMBER | |
| CHICAGO, I | L 60606 | | 2872 | | |

DATE MAILED: 11/26/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

| | | A 1! - 4! N1- | 14 | | | |
|---|--|--|---|--|--|--|
| Office Action Summary | | Application No. | Applicant(s) | | | |
| | | 10/644,555 | SHOZUDE ET AL. | | | |
| | | Examiner | Art Unit | | | |
| | | Audrey Y. Chang | 2872 | | | |
| The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply | | | | | | |
| THE - Exte after - If the - If NC - Failt Any | ORTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a reply of period for reply is specified above, the maximum statutory period we are to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b). | 6(a). In no event, however, may a reply within the statutory minimum of thirty (3 ill apply and will expire SIX (6) MONTH cause the application to become ABAN | y be timely filed 30) days will be considered timely. S from the mailing date of this communication. IDONED (35 U.S.C. § 133). | | | |
| Status | | | | | | |
| 1)🖂 | Responsive to communication(s) filed on 13 Se | entember 2004. | | | | |
| 2a)□ | This action is FINAL . 2b)⊠ This action is non-final. | | | | | |
| 3)□ | | | | | | |
| | closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213. | | | | | |
| Disposit | ion of Claims | | | | | |
| 5)□ 6)⊠ 7)□ | Claim(s) 1-27 is/are pending in the application. 4a) Of the above claim(s) 10-17 and 23-27 is/are withdrawn from consideration. Claim(s) is/are allowed. Claim(s) 1-9 and 18-22 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or election requirement. | | | | | |
| Applicat | ion Papers | | | | | |
| 10)⊠ | The specification is objected to by the Examiner The drawing(s) filed on 20 August 2003 is/are: Applicant may not request that any objection to the conference of the confere | a)⊠ accepted or b)⊡ objed Irawing(s) be held in abeyance on is required if the drawing(s) | e. See 37 CFR 1.85(a). is objected to. See 37 CFR 1.121(d). | | | |
| Priority (| under 35 U.S.C. § 119 | | | | | |
| 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) □ All b) □ Some * c) □ None of: 1. □ Certified copies of the priority documents have been received. 2. □ Certified copies of the priority documents have been received in Application No 3. □ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. | | | | | | |
| 2) Notice 3) Infor | ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) er No(s)/Mail Date 8/20/2003. | Paper No(s)/N | nmary (PTO-413) Mail Date rmal Patent Application (PTO-152) | | | |

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DETAILED ACTION

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Election/Restrictions

- 1. Applicant's election without traverse of claims 1, 5-9, 18 and 20-22 (Species A) in the reply filed on September 13, 2004 is acknowledged.
- Claims 10-17, and 23-27 are withdrawn from further consideration pursuant to 37 CFR
 1.142(b) as being drawn to a nonelected species there being no allowable generic or linking claim.
 Election was made without traverse in Paper filed on September 13, 2004.
- 3. Claims 1-9 and 18-22 remain pending in this application.

Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 1-7 and 18-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over the patent issued to Sato et al (PN. 5,181,141) in view of the patent issued to Ichikawa (PN. 4,988,164).

Sato et al teaches an anti-reflection optical element that is comprised of a plastic optical element, serves as the substrate, a foundation layer serves as the first film, a low refractive index layer, serves as the second film and a multi-layer film that is having an anti-reflective characteristics, formed on the second film (please see Figure 3). Sato et al teaches that the substrate or the plastics optical element is made of synthetic resin, (please see column 3). Sato et al also teaches that the foundation layer and the low refractive index layer, serves as the second film, formed on the surface of the foundation layer, are both made of the silicon dioxide, which known in the art has refractive index between 1.45 to 1.5, (please see column 5, lines 50-55 and column 8, lines 1-7). Sato et al also teaches explicitly the foundation layer

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is formed *directly* on the optical element or the substrate to enhance the adhesion between the substrate and the multi-layer film including the low refractive index layer as the second film, (please see column 8, lines 4-7).

This reference has met all the limitations of the claims with the exception that this reference does not teach explicitly that the refractive index of the foundation layer or the first film is the same as the refractive index of the substrate. However it is a common knowledge in the art to make layer materials having matching refractive index to reduce unwanted reflection at the interface. It is known in the art that the film structure is not desired to have reflection of light occurs at the interface between the substrate and the foundation layer, since the interference between the reflected light to provide anti-reflection property is not designed to occur at the interface. It would then have been obvious to one skilled in the art to select an resin material having refractive index equals to the refractive index of the foundation layer or first film to serve as the substrate for the benefit of reducing unwanted reflection occurred at the interface. Furthermore, with respect to claim 3, Ichikawa in the same field of endeavor teaches an anti-reflection film for synthetic resin optical element wherein acrylic resin having a refractive index of 1.49 is used as the substrate or the optical element and having the anti-reflection film formed upon it. It would then have been obvious to one skilled in the art to apply the teachings of Ichikawa to use acrylic resin as the synthetic resin for the substrate for the benefit of matching the refractive index between the substrate and the foundation layer or first film to reduce possible noise occurs at the interface since it has been held to be within the general skill of a worker in the art to select a known material on the basis of its suitability for the intended used as a matter of obvious design choice. In re Leshin, 125 USPQ 416.

With regard to claim 4, the *product by process limitation* of the claim is not given any patentable weight for the process limitation—vacuum deposition is very well known layer forming process in the art and it *does not* distinguish the product namely the anti-reflection film of the instant application from the prior art anti-reflection film. Nevertheless, with respect to claim 18, Sato et al teaches that the foundation

form the film with this process.

layer and the multi-layer film including the second film can be formed by standard vapor deposition or vacuum deposition process, (please see column 6, lines 23-28). Ichikawa further teaches that the oxide layers for the anti-reflective film including the silicon dioxide layer can be formed by vacuum deposition process using resistance heating, (please see Figure 2). It would then have been obvious to one skilled in the art to apply the teachings of both Sato et al and Ichikawa to use standard vacuum deposition with resistance heating process to deposit the oxide layer for it is well know and standard practice in the art to

With regard to claims 5-7 and 20, Sato et al teaches that the multi-layer anti-reflective film comprises a high/low refractive index layer alternative arrangement and comprises a third layer material, namely the high refractive index layer, that is made either of *tantalum oxide* (Ta₂O₅) or *zirconium oxide* (ZrO₂), which implicitly has the refractive index between the range of 2.2 to 2.4, (please see column 5, line 42 to column 6 line 12).

6. Claims 8-9 and 21-22 are rejected under 35 U.S.C. 103(a) as being unpatentable over the patents issued to Sato et al and Ichikawa as applied to claims 1 and 18 above, and further in view of the patent issued to Nakahigashi et al (PN. 5,562,952).

The anti-reflective film taught by Sato et al in combination with the teachings of Ichikawa as described for claims 1 and 18 above have met all the limitations of the claims.

With regard to claims 8-9, the *product-by-process limitations* concerning the forming process of the third film are not given any patentable weight since the process relined upon, namely the *plasma* deposition process is rather well known process in the art, and the process limitations do not distinguish the final product, namely the high refractive index layer formed in the multi-layer anti-reflective film, of the instant application from the prior art. Nevertheless, the features are addressed with regard to the process claims 21-22. Sato et al teaches that the layer in the multi-layer anti-reflection film can be

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formed by vapor deposition process or vacuum deposition process, however it does not teach explicitly that it can also be formed by the plasma CVD process.

Nakahigashi et al in the same field of endeavor teaches that plasma CVD film deposition method is quite well known in the art. The process and the apparatus can be used to deposit film layer such as zirconium oxide (ZrO₂), tantalum oxide (Ta₂O₅) and titanium dioxide (TiO₂), (please see column 6, lines 60-62). The plasma CVD deposition apparatus and method including a vacuum chamber (10, Figures 15-16), an electrode (20) having a substrate (S1) placed on it, a film forming material is evaporated within the chamber using gas source supply (40) and an radio frequency power source (320) applied at the supply electrode (30) to convert the gas to *plasma* within the chamber, (please see columns 1-3). Nakahigashi et al teaches that the RF power is of a frequency of 13.56MHz. It would then have been obvious to one skilled in the art to use the standard plasma CVD film deposition process to deposit the high refractive index layer of the anti-reflective layer as an alternative method for forming the antireflection film since both the vacuum deposition method and plasma CVD deposition method are well known film forming process in the art to use one over the other would have been obvious matters of design choice to one skilled in the art. The bias voltage value for the RF power source as recited in claims 9 and 22 is considered to be either inherently met by the disclosure for actually forming the layer, or an obvious matters of design choice to one skilled in the art for the benefit of selecting the voltage value to complete the deposition process.

Contact Information

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Audrey Y. Chang whose telephone number is 571-272-2309. The examiner can normally be reached on Monday-Friday (8:00-4:30), alternative Mondays off.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Drew Dunn can be reached on 571-272-2312. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Audrey Y. Chang Primary Examiner Art Unit 2872

A. Chang, Ph.D.